



# STL17N3LLH6

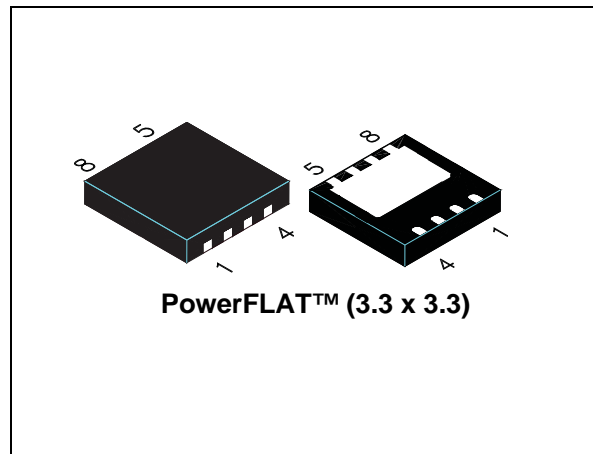
N-channel 30 V, 0.0038  $\Omega$ , 17 A PowerFLAT™(3.3x3.3)  
STripFET™ VI DeepGATE™ Power MOSFET

## Features

Order code	V <sub>DSS</sub>	R <sub>DS(on)</sub> max.	I <sub>D</sub>
STL17N3LLH6	30 V	0.0045 $\Omega$	17 A <sup>(1)</sup>

1. The value is rated according R<sub>thj-pcb</sub>

- R<sub>DS(on)</sub> \* Q<sub>g</sub> industry benchmark
- Extremely low on-resistance R<sub>DS(on)</sub>
- High avalanche ruggedness
- Low gate drive power losses
- Very low switching gate charge



## Application

Switching applications

## Description

This product utilizes the 6<sup>th</sup> generation of design rules of ST's proprietary STripFET™ technology, with a new gate structure. The resulting Power MOSFET exhibits the lowest R<sub>DS(on)</sub> in a standard package, that makes it suitable for the most demanding DC-DC converter applications, where high power density has to be achieved.

Figure 1. Pin-out configuration

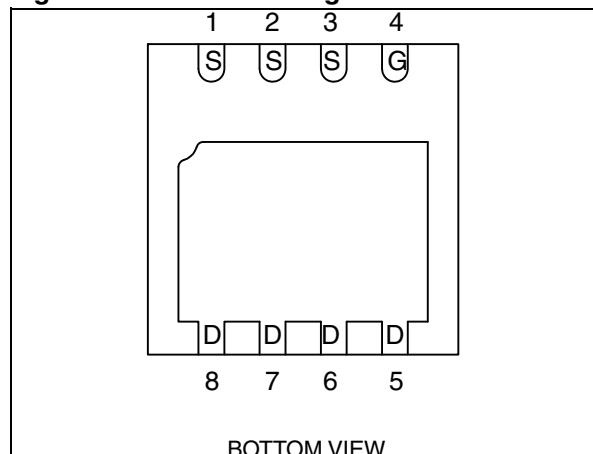


Table 1. Device summary

Order code	Marking	Package	Packaging
STL17N3LLH6	17N3L	PowerFLAT™ (3.3 x 3.3)	Tape and reel

# Contents

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# 1 Electrical ratings

**Table 2. Absolute maximum ratings**

Symbol	Parameter	Value	Unit
$V_{DS}$	Drain-source voltage ( $V_{GS} = 0$ )	30	V
$V_{GS}$	Gate-source voltage	$\pm 20$	V
$I_D^{(1)}$	Drain current (continuous) at $T_C = 25\text{ }^\circ\text{C}$	17	A
$I_D^{(1)}$	Drain current (continuous) at $T_C = 100\text{ }^\circ\text{C}$	11	A
$I_{DM}^{(2)}$	Drain current (pulsed)	68	A
$P_{TOT}^{(3)}$	Total dissipation at $T_C = 25\text{ }^\circ\text{C}$	50	W
$P_{TOT}^{(1)}$	Total dissipation at $T_C = 25\text{ }^\circ\text{C}$	2	W
	Derating factor	0.03	W/ $^\circ\text{C}$
$T_J$	Operating junction temperature	-55 to 150	$^\circ\text{C}$
$T_{stg}$	Storage temperature		

1. The value is rated according  $R_{thj-pcb}$
2. Pulse width limited by safe operating area
3. The value is rated according  $R_{thj-c}$

**Table 3. Thermal resistance**

Symbol	Parameter	Value	Unit
$R_{thj-case}$	Thermal resistance junction-case (drain) (steady state)	2.5	$^\circ\text{C}/\text{W}$
$R_{thj-pcb}^{(1)}$	Thermal resistance junction-pcb	42.8	$^\circ\text{C}/\text{W}$
$R_{thj-pcb}^{(2)}$	Thermal resistance junction-pcb	63.5	$^\circ\text{C}/\text{W}$

1. When mounted on FR-4 board of 1inch<sup>2</sup>, 2oz Cu,  $t < 10$  sec
2. Steady state

## 2 Electrical characteristics

( $T_{CASE} = 25\text{ °C}$  unless otherwise specified)

**Table 4. On/off states**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$V_{(BR)DSS}$	Drain-source breakdown voltage	$I_D = 250\ \mu\text{A}$ , $V_{GS} = 0$	30			V
$I_{DSS}$	Zero gate voltage drain current ( $V_{GS} = 0$ )	$V_{DS} = \text{Max rating}$ , $V_{DS} = \text{Max rating @ } 125\text{ °C}$			1 10	$\mu\text{A}$ $\mu\text{A}$
$I_{GSS}$	Gate body leakage current ( $V_{DS} = 0$ )	$V_{GS} = \pm 20\text{ V}$			$\pm 100$	nA
$V_{GS(th)}$	Gate threshold voltage	$V_{DS} = V_{GS}$ , $I_D = 250\ \mu\text{A}$	1			V
$R_{DS(on)}$	Static drain-source on resistance	$V_{GS} = 10\text{ V}$ , $I_D = 8.5\text{ A}$ $V_{GS} = 4.5\text{ V}$ , $I_D = 8.5\text{ A}$		0.0038 0.0057	0.0045 0.0073	$\Omega$ $\Omega$

**Table 5. Dynamic**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$C_{iss}$	Input capacitance	$V_{DS} = 25\text{ V}$ , $f = 1\text{ MHz}$ , $V_{GS} = 0$	-	1690	-	pF
$C_{oss}$	Output capacitance			290		pF
$C_{rss}$	Reverse transfer capacitance			176		pF
$Q_g$	Total gate charge	$V_{DD} = 15\text{ V}$ , $I_D = 17\text{ A}$ $V_{GS} = 4.5\text{ V}$ (see Figure 14)	-	17	-	nC
$Q_{gs}$	Gate-source charge			8		nC
$Q_{gd}$	Gate-drain charge			6		nC
$R_G$	Gate input resistance	$f = 1\text{ MHz}$ Gate DC Bias = 0 Test signal level = 20 mV open drain	-	1.7	-	$\Omega$

**Table 6. Switching times**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$t_{d(on)}$	Turn-on delay time	$V_{DD} = 15\text{ V}$ , $I_D = 8.5\text{ A}$ , $R_G = 4.7\ \Omega$ , $V_{GS} = 10\text{ V}$ (see Figure 13)	-	9.5	-	ns
$t_r$	Rise time			30		ns
$t_{d(off)}$	Turn-off delay time			37		ns
$t_f$	Fall time			12		ns

**Table 7. Source drain diode**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$I_{SD}$	Source-drain current		-		17	A
$I_{SDM}^{(1)}$	Source-drain current (pulsed)		-		68	A
$V_{SD}^{(2)}$	Forward on voltage	$I_{SD} = 17\text{ A}, V_{GS} = 0$	-		1.1	V
$t_{rr}$	Reverse recovery time	$I_{SD} = 17\text{ A},$ $di/dt = 100\text{ A}/\mu\text{s},$ $V_{DD} = 25\text{ V}$	-	24		ns
$Q_{rr}$	Reverse recovery charge			16.8		nC
$I_{RRM}$	Reverse recovery current			1.4		A

1. Pulse width limited by safe operating area.
2. Pulsed: pulse duration=300 $\mu\text{s}$ , duty cycle 1.5%

## 2.1 Electrical characteristics (curves)

Figure 2. Safe operating area

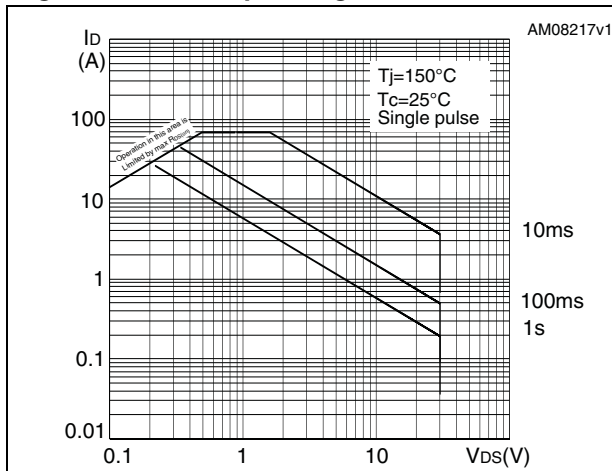


Figure 3. Thermal impedance

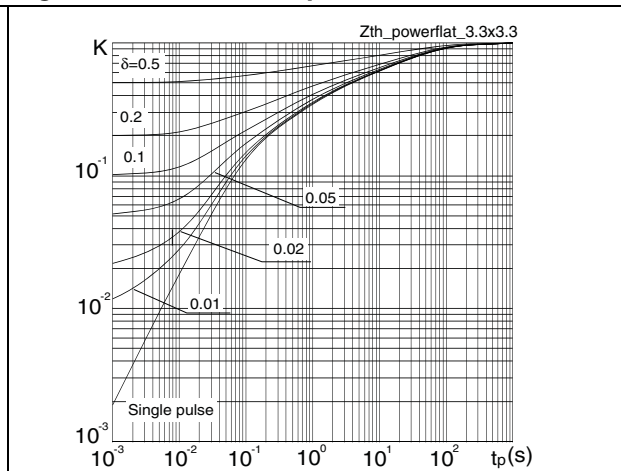


Figure 4. Output characteristics

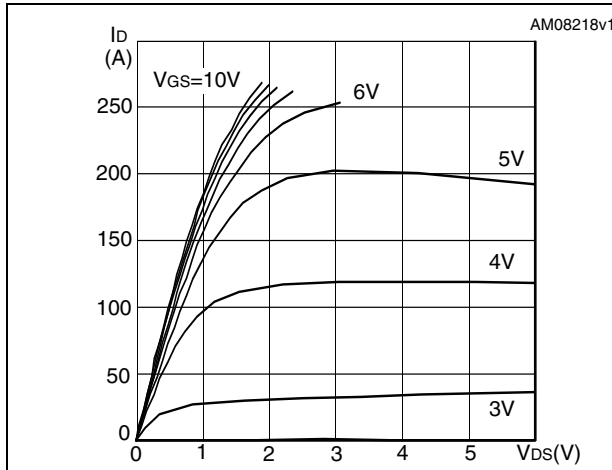


Figure 5. Transfer characteristics

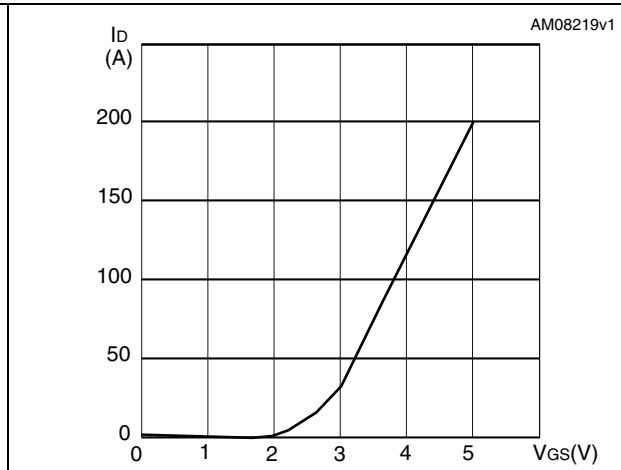


Figure 6. Normalized  $B_{V_{DSS}}$  vs temperature

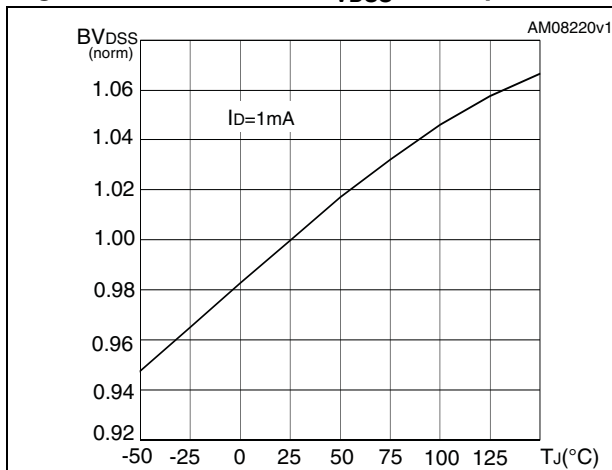


Figure 7. Static drain-source on resistance

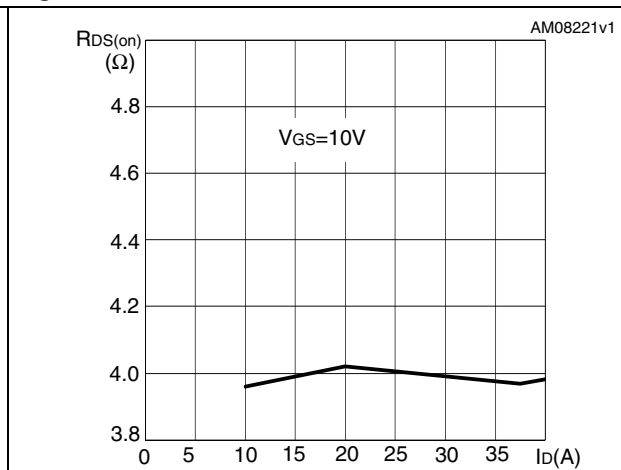


Figure 8. Gate charge vs gate-source voltage Figure 9. Capacitance variations

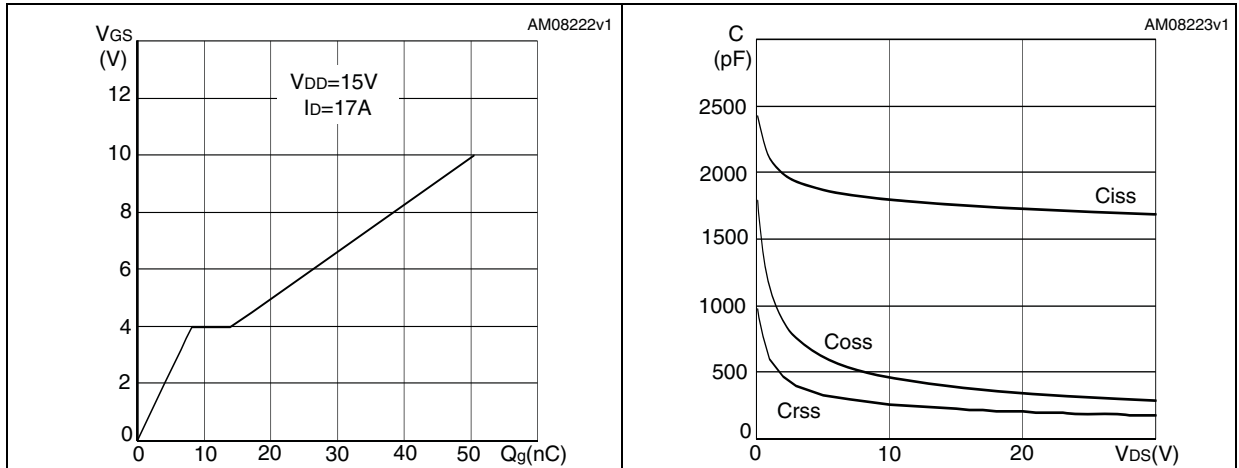


Figure 10. Normalized gate threshold voltage vs temperature Figure 11. Normalized on resistance vs temperature

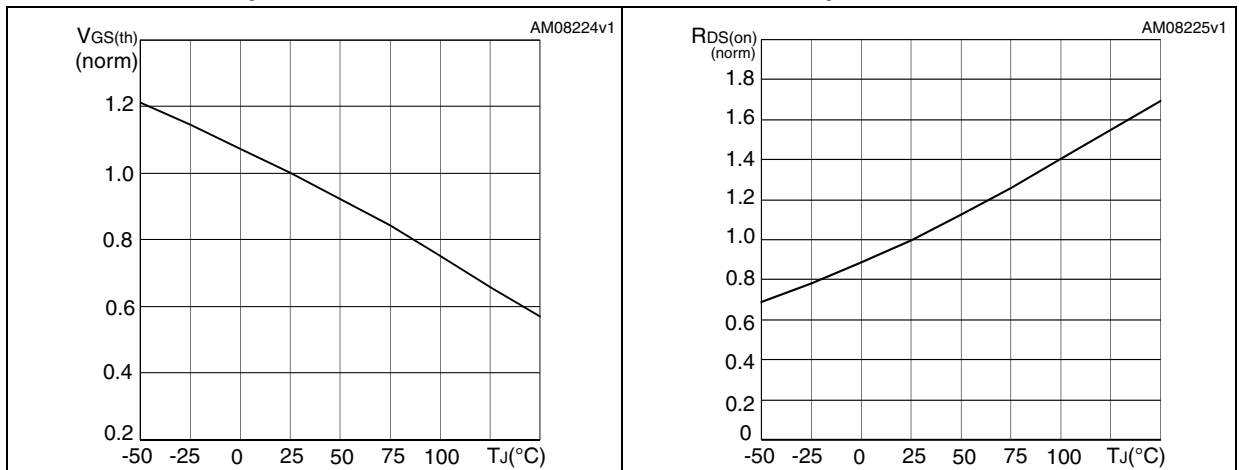
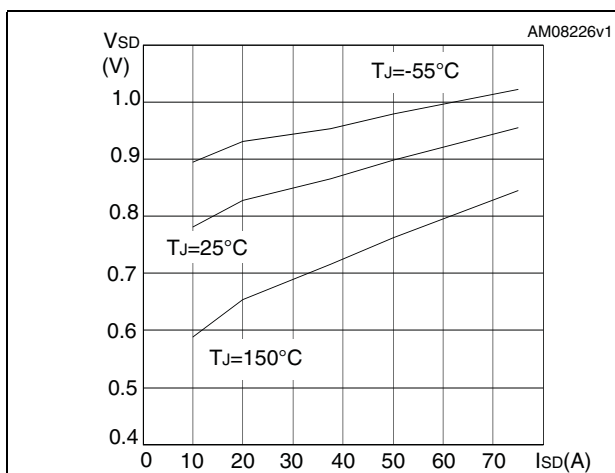
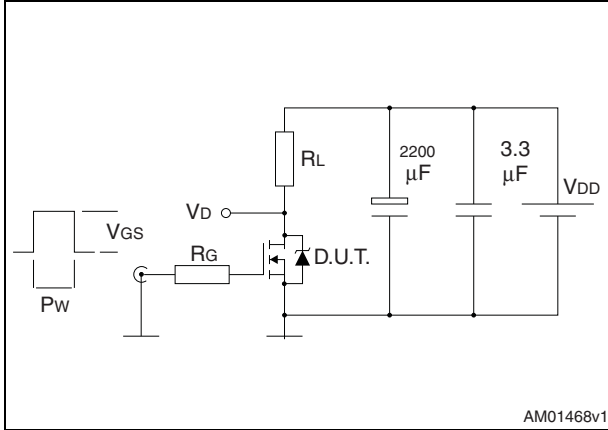


Figure 12. Source-drain diode forward characteristics



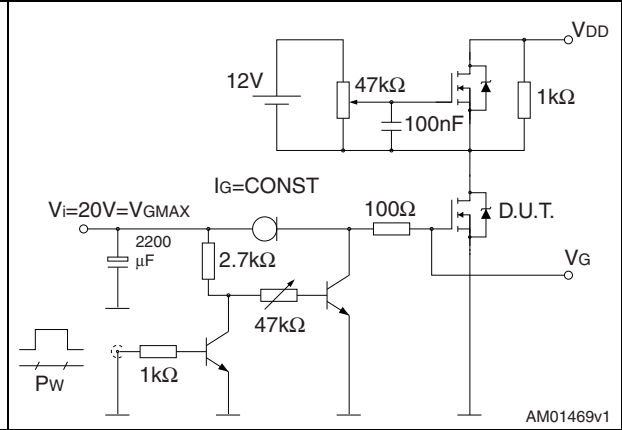
### 3 Test circuits

**Figure 13. Switching times test circuit for resistive load**



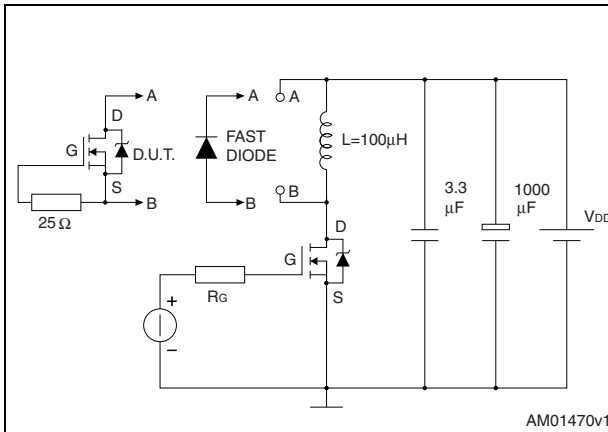
AM01468v1

**Figure 14. Gate charge test circuit**



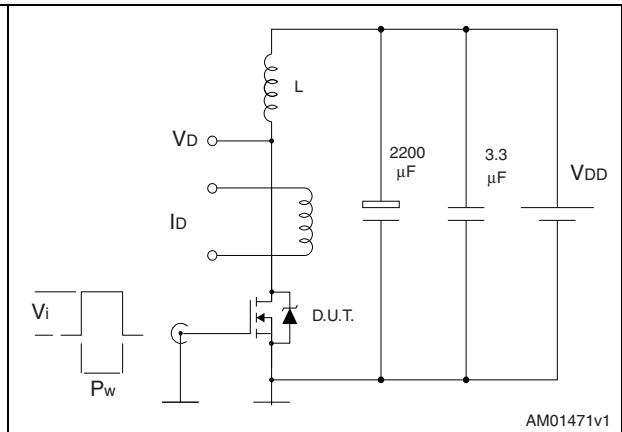
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**Figure 15. Test circuit for inductive load switching and diode recovery times**



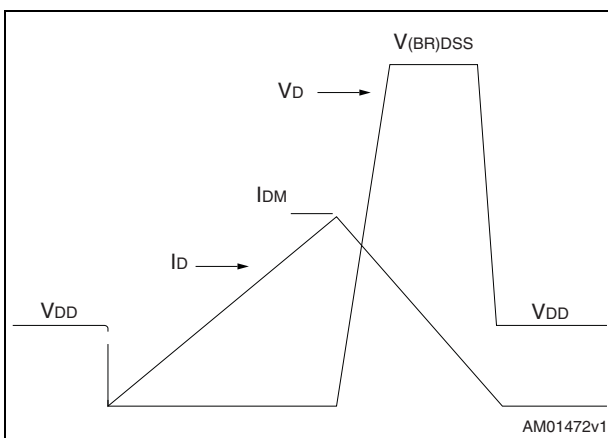
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**Figure 16. Unclamped inductive load test circuit**



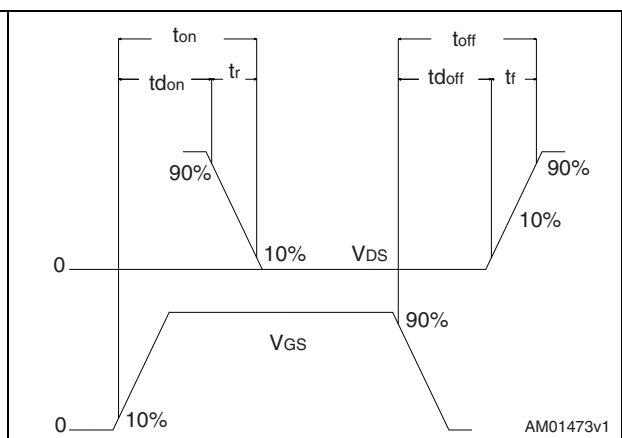
AM01471v1

**Figure 17. Unclamped inductive waveform**



AM01472v1

**Figure 18. Switching time waveform**



AM01473v1



## 4 Package mechanical data

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: [www.st.com](http://www.st.com). ECOPACK is an ST trademark.

**Table 8. Package dimensions**

Dim.	mm.		
	Min.	Typ	Max.
A	0.80	0.90	1.00
A1		0.02	0.05
b	0.25	0.30	0.35
D		3.30	
D2	2.50	2.65	2.75
e		0.65	
E		3.30	
E2	1.76	1.91	2.01
L	0.30	0.40	0.50

Figure 19. Package drawing

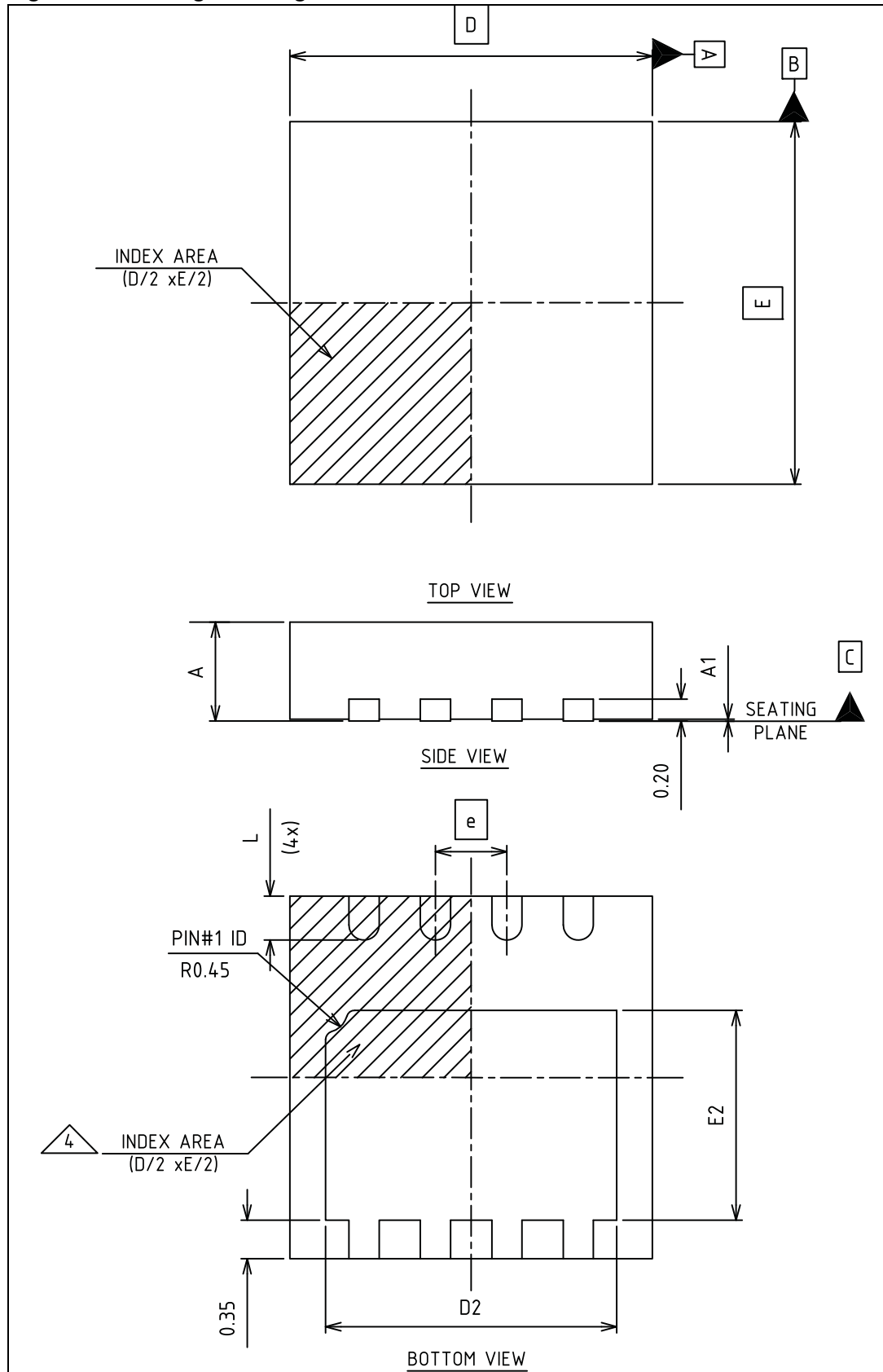
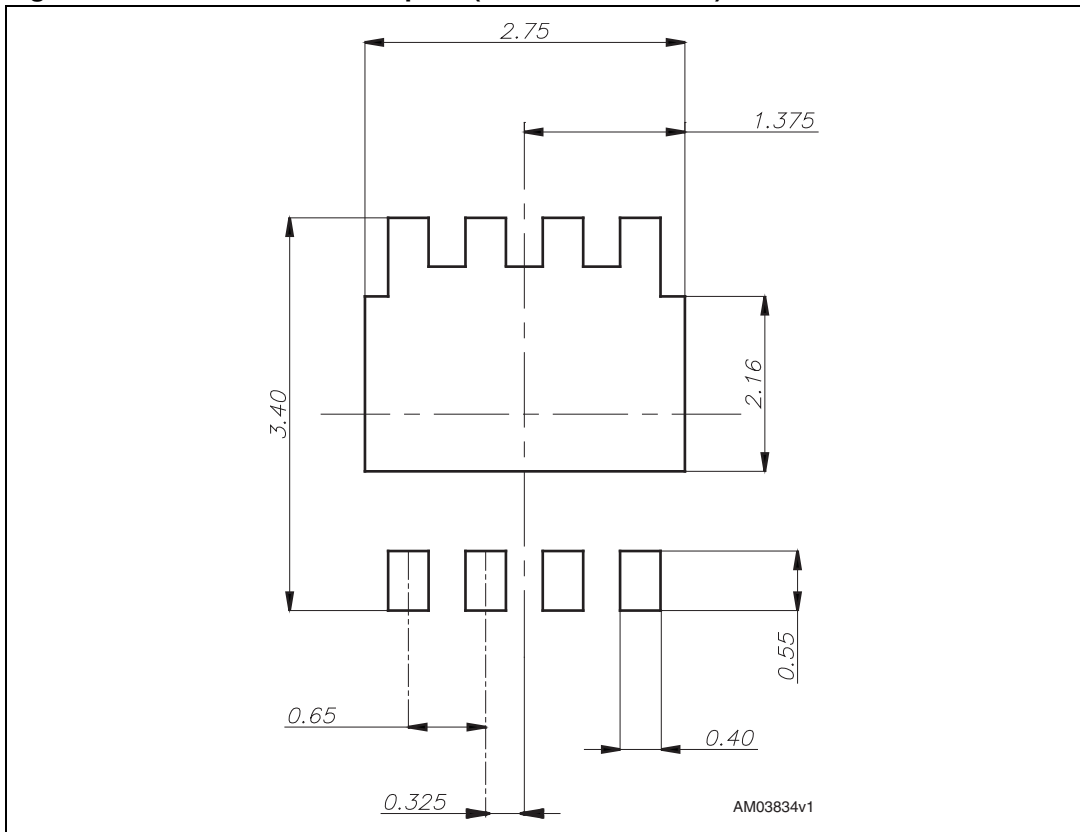


Figure 20. Recommended footprint (dimensions in mm)



## 5 Revision history

**Table 9. Document revision history**

Date	Revision	Changes
24-Mar-2009	1	First release.
06-Jul-2010	2	Updated <a href="#">Table 4: On/off states</a> .
10-Nov-2010	3	Document status promoted from preliminary data to datasheet.

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